

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4672229

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Liang Yi	10/27/2017
Che-Jung Hsu	10/27/2017
Yu-Cheng Tung	10/31/2017
JIANJUN YANG	10/27/2017
Yuan-Hsiang Chang	10/27/2017
Chih-Chien Chang	10/27/2017
WEICHANG LIU	10/25/2017
Shen-De Wang	10/30/2017
KOK WUN TAN	10/27/2017
RECEIVING PARTY DATA	
Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15802450
CORRESPONDENCE DATA	
Fax Number:	(703)997-4517
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3027291562
Email:	Patent.admin.uspto.cr@naipo.com
Correspondent Name:	WINSTON HSU
Address Line 1:	5F., NO.389, FUHE RD., YONGHE DIST.,
Address Line 4:	NEW TAIPEI CITY, TAIWAN
ATTORNEY DOCKET NUMBER:	NAUP3176USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/

DATE SIGNED:

11/02/2017

Total Attachments: 18

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COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

FINFET SEMICONDUCTOR DEVICES AND METHOD OF MANUFACTURING THE SAME IN MEMORY REGIONS AND LOGIC REGIONS

As the below named inventor, I hereby declare that:
This declaration is directed to:

- The attached application, or
- United States application number _____ filed on _____, or
- PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS CORP.** having a postal address of _____

No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, I have hereunto set hand and seal this OCT 27 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Liang Yi**

Date: 2017-10-27

Signature: Yi Liang

UMC 2017/10/17 14:01:46 00071544

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Che-Jung Hsu**

Date: 2017-10-27

Signature: Che Jung Hsu

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**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention:

**FINFET SEMICONDUCTOR DEVICES AND METHOD OF MANUFACTURING THE
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In consideration of the payment by **UNITED MICROELECTRONICS** having a postal address of **CORP.**

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IN WITNESS WHEREOF, I have hereunto set hand and seal this OCT 31 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yu-Cheng Tung**

Date: **OCT 31 2017**

Signature:

Yu-Cheng Tung

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

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IN WITNESS WHEREOF, I have hereunto set hand and seal this OCT 27 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **JIANJUN YANG**

Date: 2017-10-27

Signature: Yang Jianjun

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**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention:

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Yuan-Hsiang Chang**

Date: 2017-10-27

Signature: Yuan Hsiang Chang

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COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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IN WITNESS WHEREOF, I have hereunto set hand and seal this OCT 27 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chih-Chien Chang**

Date:

2017-10-27

Signature:

Chang Chih Chien

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COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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IN WITNESS WHEREOF, I have hereunto set hand and seal this OCT 25 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **WEICHANG LIU**

Date: 2017/10/25

Signature: LIU WEI CHANG

UMC 2017/10/17 14:01:46 00071544

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Shen-De Wang**

Date: 2017-10-30

Signature: Wang Shen De

UMC 2017/10/17 14:01:46 000713

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

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LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **KOK WUN TAN**

Date: 2017-10-27

Signature: _____

Kok Wun Tan

UNAS 2017/10/27 14:01:46 00071544